



规格书编号

SPEC NO:

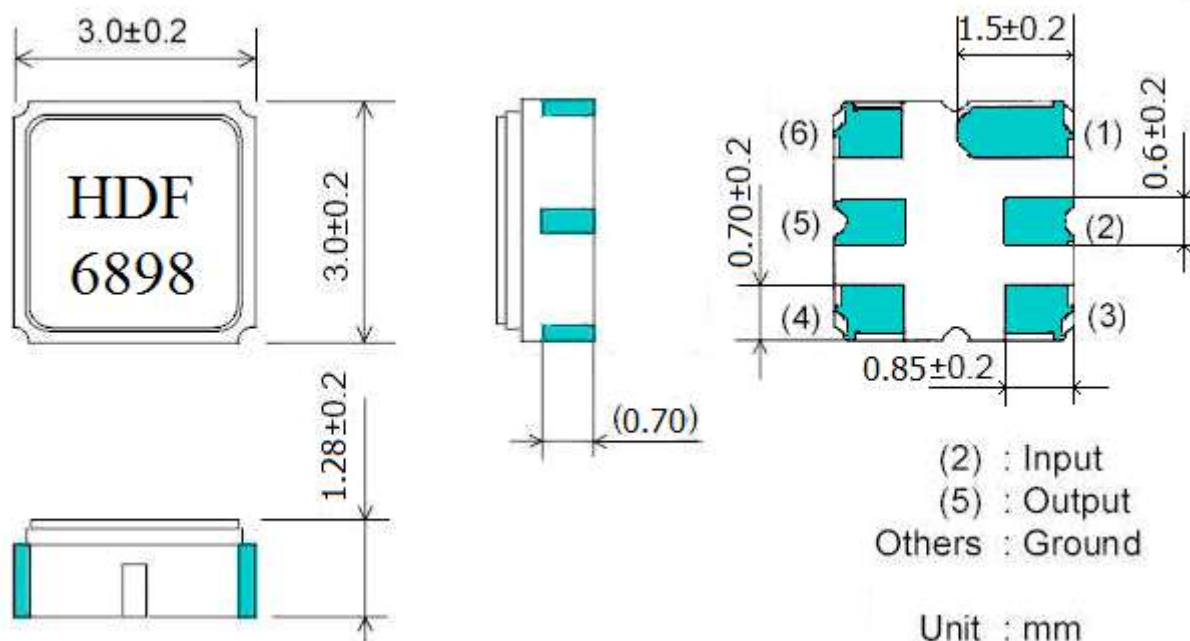
产品规格书 SPECIFICATION

CUSTOMER 客 户: _____
PRODUCT 产 品: _____ SAW FILTER
MODEL NO 型 号: _____ HDF835A3-S6
MARKING 印 字: _____ HDF6898
PREPARED 编 制: _____ CHECKED 审 核: _____
APPROVED 批 准: _____ D A T E 日 期: _____ 2012-12-3

客户确认 CUSTOMER RECEIVED:		
审核 CHECKED	批准 APPROVED	日期 DATE

无锡市好达电子有限公司
Shoulder Electronics Limited

1. Package Dimension



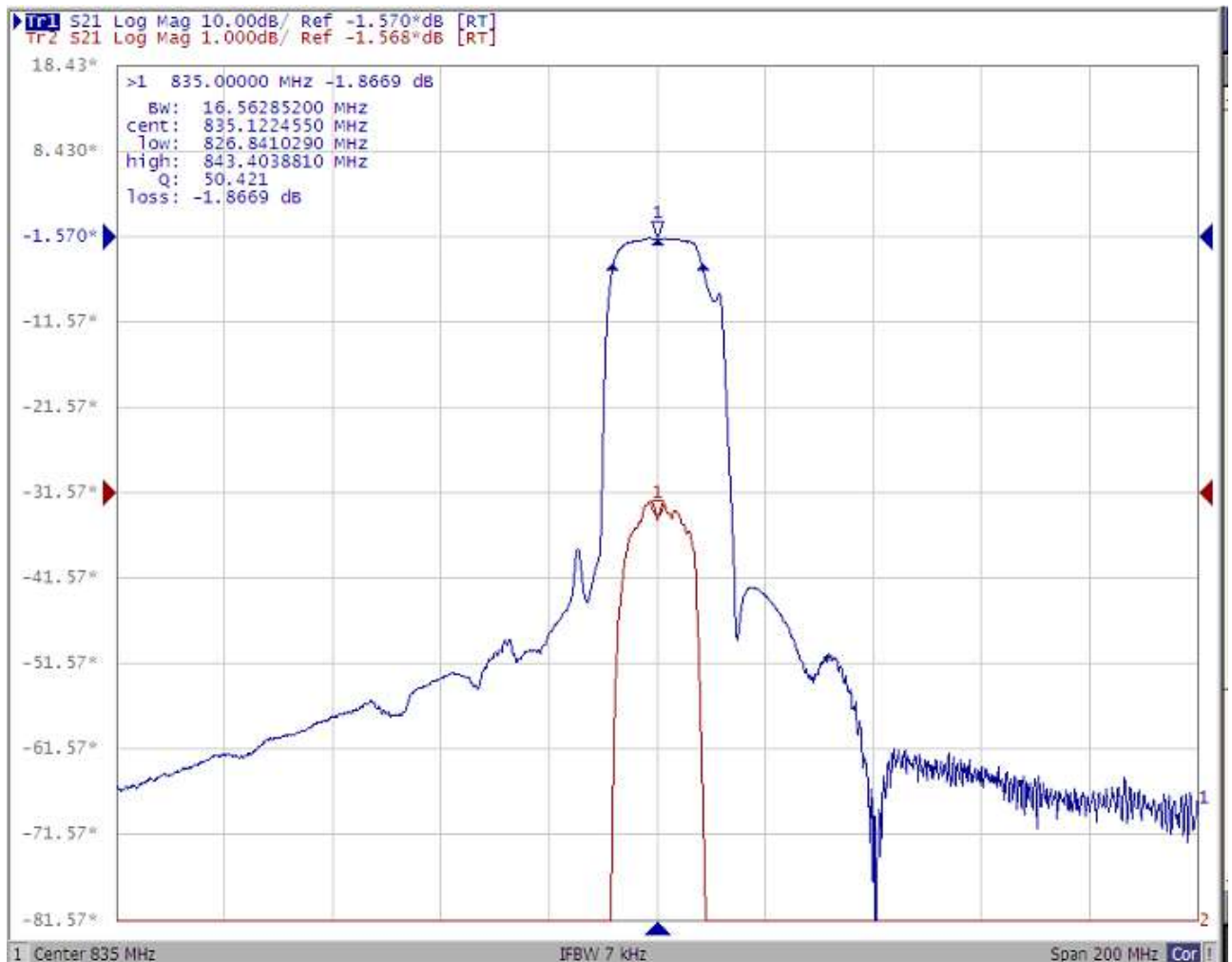
2. Performance

2.1 Maximum Rating

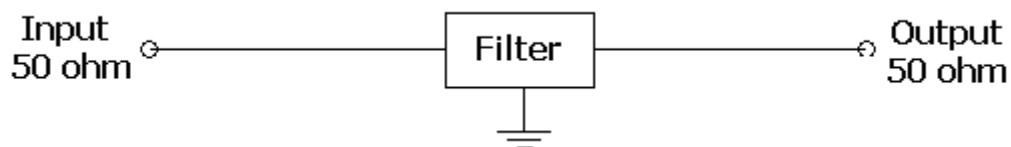
DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Operation temperature	-45℃ to +85℃
Storage temperature	-45℃ to +85℃
RF Power Level	10dBm

2.2 Electronic Characteristics

	Unit	Minimum	Typical	Maximum
Center Frequency	MHz	-	835	-
Insertion Loss (830~840MHz)	dB		2.0	3.5
Amplitude Ripple (830~840MHz)	dB		0.5	1.5
VSWR(830~840MHz)			1.5	-
Relative Attenuation				
0~800 MHz	dB	40	55	-
870~1300MHz	dB	40	55	-
Input/Output Impedance	Ohms		50	



3. TEST CIRCUIT



4. ENVIRONMENTAL CHARACTERISTICS

4-1 Temperature cycling

Subject the device to a low temperature of -45°C for 30 minutes. Following by a high temperature of +25°C for 5 Minutes and a higher temperature of +85°C for 30 Minutes. Then release the device into the room conditions for 1 to 2 hours prior to the measurement. It shall meet the specifications in 3.3.

4-2 Resistance to solder heat

Submerge the device terminals into the solder bath at 260°C ± 5°C for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. It shall meet the specifications in 3.3.

4-3 Solderability

Submerge the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the soldering pad must be covered with new solder. It shall meet the specifications in 3.3.

4-4 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1 m 3 times. the filter shall fulfill the specifications in 3.3.

4-5 Vibration

Subject the device to the vibration for 2 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 hz. The filter shall fulfill the specifications in 3.3.

5. REMARK

5.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

5.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

5.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.

6. Packing

6.1 Dimensions

(1) Carrier Tape: Figure 1

(2) Reel: Figure 2

(3) The product shall be packed properly not to be damaged during transportation and storage.

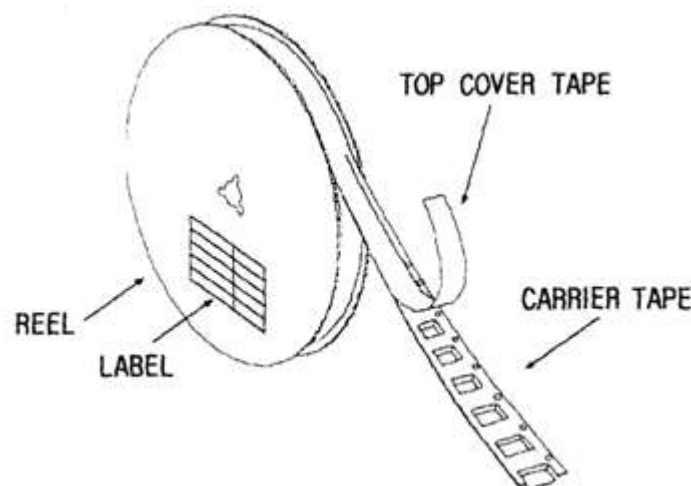
6.2 Reeling Quantity

1000 pcs/reel 7"

3000 pcs/reel 13"

6.3 Taping Structure

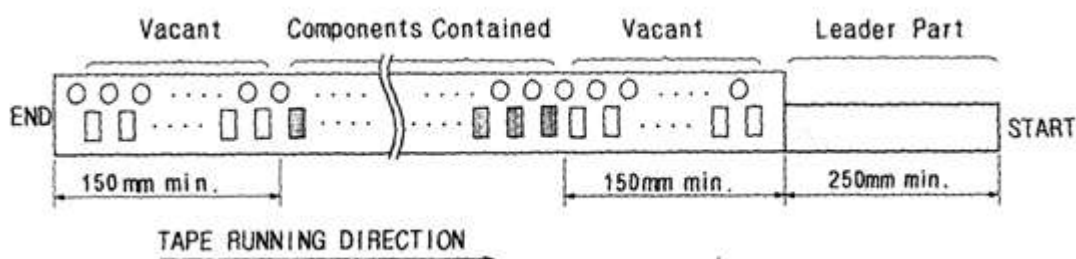
(1) The tape shall be wound around the reel in the direction shown below.



(2) Label

Device Name	
User Product Name	
Quantity	
Lot No.	

(3) Leader part and vacant position specifications.



7. TAPE SPECIFICATIONS

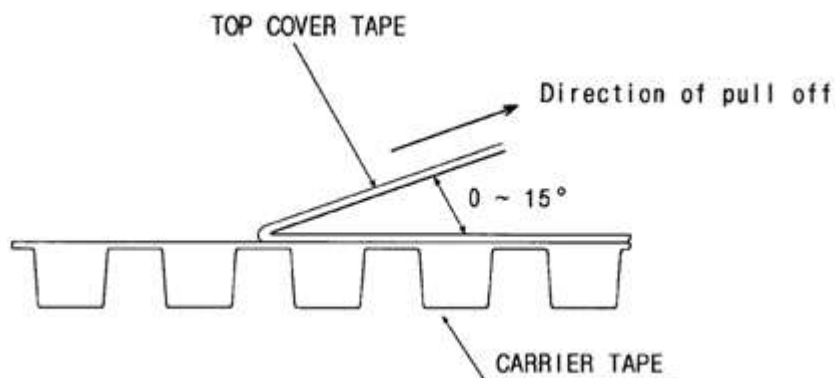
7.1 Tensile Strength of Carrier Tape: 4.4N/mm width

7.2 Top Cover Tape Adhesion (See the below figure)

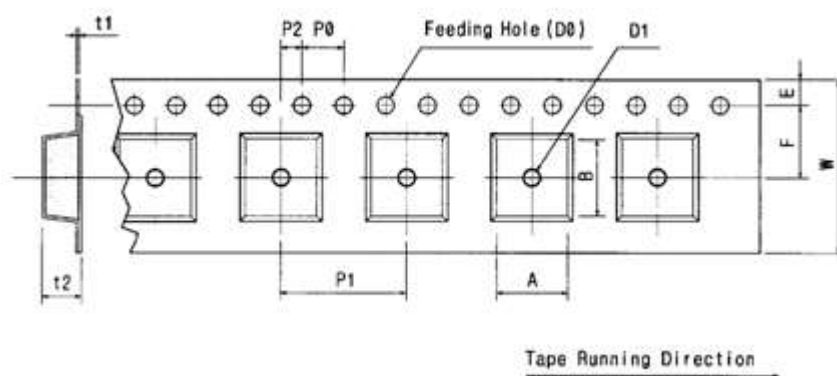
(1) pull off angle: $0 \sim 15^\circ$

(2) speed: 300mm/min.

(3) force: 20~70g



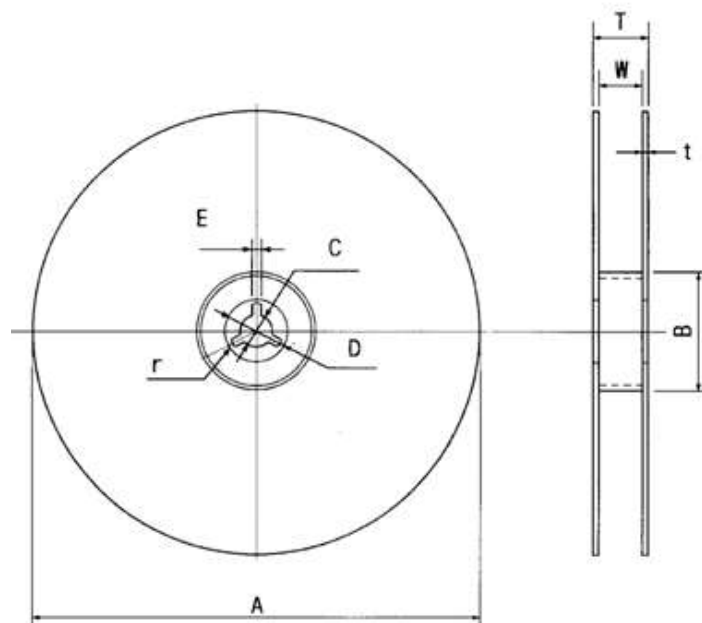
[Figure 1] Carrier Tape Dimensions



[Unit:mm]

W	F	E	P0	P1	P2	D0	D1	t1	t2	A	B
12.00	5.50	1.75	4.00	8.00	2.00	Ø1.50	Ø1.0	0.25	1.65	4.04	4.10
±0.30	±0.10	±0.10	±0.10	±0.10	±0.10		±0.25	±0.05	±0.10	±0.10	±0.10

[Figure 2]



[Unit:mm]

A	B	C	D	E	W	t	r
Ø330	Ø100	Ø13	Ø21	2	13	3	1.0
±1.0	±0.5	±0.5	±0.8	±0.5	±0.3	max.	max.